

Product Change Notification

MultiTech Dragonfly™ 3G HSPA+ Embedded Cellular Modems and SoMs

Date: February 4, 2020

I. Product Change Notification Number (PCN)

PCN 02042020-00

II. Impacted Products

MTQ-H5-B01	HSPA+ Embedded Cellular SoM w/GPS (50 Pk)
MTQ-H5-B01-SP	HSPA+ Embedded Cellular SoM w/GPS (1 Pk)
MTQ-H5-B02	Embedded HSPA+ Modem w/GPS (50 Pk)
MTQ-H5-B02-SP	Embedded HSPA+ Modem w/GPS (1 Pk)

III. Type of Change and Reason

Minor Printed Circuit Board (PCB) revision to accommodate a new micro SIM holder.

MultiTech has completed a minor board revision to the PCB used for the Dragonfly MTQ-H5-B0x family. The revision was needed to provide a SIM holder that has been identified as being more reliable. The spring mechanism in the old SIM holder may fail with repeated SIM insertions and ejections. The location for the SIM holder opening has not changed. (See drawings in Section IV)

Any MTQ-H5-B0x with a Date of Manufacture (DOM) of February 3, 2020 or later will include the new PCB and SIM holder.

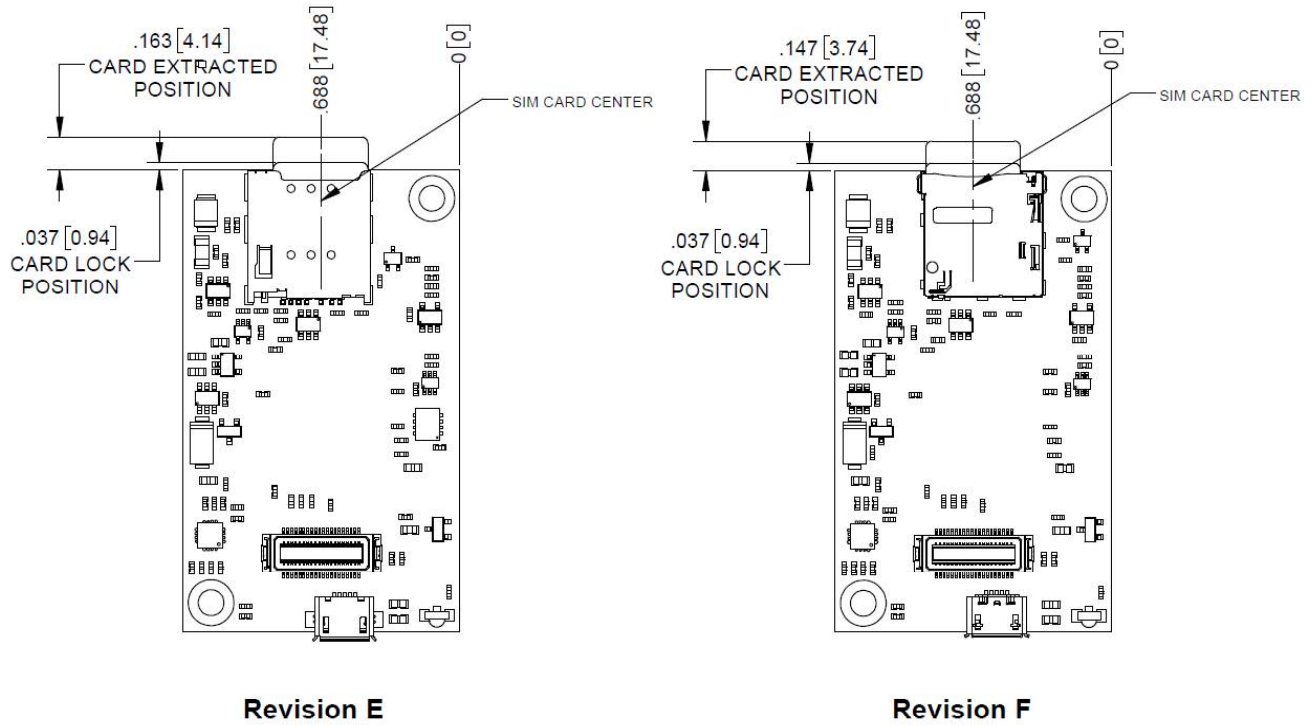
IV. Current and New PCB Versions

Current PCB Version

Rev. E

New PCB Version

Rev. F



V. Additional Information

If you have any questions regarding this Product Change Notification, please contact your MultiTech sales representative:

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